AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A method of manufacturing a laminated ceramic electronic component comprising the steps of:

preparing a first transfer sheet including a composite green sheet supported by a first supporting film, said composite green sheet ~~having~~ including a conductor formed on a region of the first transfer sheet and at least one of a first ceramic area and a second ceramic area formed ~~in~~ on another region of the first transfer sheet excluding a ~~location~~the region of the first transfer sheet where the conductor is ~~provided~~formed such that the conductor and the at least one of the first ceramic area and the second ceramic area do not overlap each other;

preparing a second transfer sheet including a ceramic green sheet supported by a second supporting film;

a first transfer step of transferring the ceramic green sheet of at least one second transfer sheet on a lamination stage;

a second transfer step of transferring the composite green sheet of at least one first transfer sheet on the at least one ceramic green sheet that was previously laminated;

a third transfer step of transferring the ceramic green sheet of at least one second transfer sheet on the composite green sheet that was previously laminated; and

firing a laminate obtained by the first, second and third transfer steps.

Claim 2 (original): A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein a plurality of the first transfer sheets are prepared, and the conductors are formed so that by laminating, the conductors of the plurality of the composite green sheets are electrically connected to form a coil.

Claim 3 (original): A method of manufacturing a laminated ceramic electronic component according to claim 2, wherein at least one of the plurality of the conductors is a via hole electrode for connecting the upper and lower conductors.

Claim 4 (currently amended): A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the first ceramic area is made of a magnetic ceramic, and ~~a~~ the second ceramic area is made of a non-magnetic ceramic.

Claim 5 (original): A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the ceramic green sheet of the second transfer sheet is made of a magnetic ceramic.

Claim 6 (original): A method of manufacturing a laminated ceramic electronic component according to claim 4, further comprising the step of forming the first ceramic area and the second ceramic area by printing a magnetic ceramic paste and a non-magnetic ceramic paste, respectively.

Claim 7 (currently amended): A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming the at least one of the first ceramic area and the ~~at least one~~ second ceramic area at a ~~location~~ region excluding a region where a via hole electrode is to be formed; and

thereafter filling the region where the via hole is to be formed with an electrically conductive paste to form the via hole electrode.

Claim 8 (original): A method of manufacturing a laminated ceramic electronic component according to claim 3, further comprising the steps of:

forming a through hole in which a via hole electrode is to be formed after preparing the composite ceramic green sheet; and

filling the through hole with an electrically conductive paste to form the via hole electrode.

Claim 9 (original): A method of manufacturing a laminated ceramic electronic component according to claim 1, further comprising the steps of:

preparing a third transfer sheet in which a second composite green sheet having a magnetic ceramic area and a non-magnetic ceramic area is supported by a third supporting film; and

transferring the second composite green sheet from at least one third transfer sheet between the first transfer step and the third transfer step.

Claim 10 (original): A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common mode choke coil.

Claim 11 (previously presented): A method of manufacturing a laminated ceramic electronic component according to claim 1, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil inductor.

Claim 12 (original): A laminated ceramic electronic component comprising a sintered ceramic body produced according to the method as set forth in claim 1, and a plurality of external electrodes disposed on the outer surface of the sintered ceramic body and electrically connected to the conductors in the sintered ceramic body.

Claim 13 (original): A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is a closed magnetic circuit type laminated common mode choke coil.

Claim 14 (previously presented): A laminated ceramic electronic component according to claim 12, wherein the laminated ceramic electronic component is an open magnetic circuit type laminated common mode choke coil inductor.